

Kaladex® PEN Films





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Kaladex° PEN films can be handled and processed in a similar way to more familiar films based on polyethylene terephthalate (PET), but the distinct polymer chemistry of PEN provides several superior properties including greater resistance to heat and hydrolysis, better dimensional stability and higher modulus.

This property set has allowed the development of a range of films that provide cost-effective solutions with an enhanced performance level between that of PET films such as Mylar* and Melinex*, and high-performance but higher cost engineered films such as polyimides, for example Kapton* from DuPont.

Kaladex® PEN films are manufactured using the same stenter processes as Mylar® and Melinex® PET films. They are also biaxially oriented and heat-set to give an optimum balance of crystalline and amorphous regions, providing mechanical and thermal resilience combined with toughness and flexibility. These familiar properties are coupled with enhanced performance in terms of:

- Higher glass transition temperature (Tg) of 121°C (as resin) vs 78°C for PET
- Superior long term ageing performance at elevated temperatures, with a Relative Temperature Index (RTI) to UL746B of 160°C (mechanical) and 180°C (electrical), exceeding that required for Class F electrical insulation applications
- Better dimensional stability at elevated temperatures, in terms of lower shrinkage and better retention of mechanical properties
- Stiffness (Young's modulus)
 25% higher than PET
- Improved resistance to hydrolysis and alkalis compared to standard PET
- Very low levels of extractable oligomers for hermetic motor applications
- Inherent screening of UV light below 380nm.

The resulting balance between performance and cost makes Kaladex® PEN films well suited to a wide range of applications including electrical insulation, flexible printed circuits, capacitors, and a range of high-performance industrial applications including belts, casting substrates, speciality packaging and several emerging technologies such as EVs, batteries and fuel cells.

The leading expertise of DuPont Teijin Films in polymer science and film manufacturing technology combined with 30 years of experience with PEN films provide the basis for a highly attractive product range. Kaladex* PEN films offer:

- New and expanded market opportunities in applications with technical requirements beyond the limits of PET performance and where it is uneconomical to use higher cost materials.
- Reduced manufacturing costs with reduced wastage, increased production yields and better throughput in critical applications.
- Reduced material costs by avoiding the use of over-specified materials.

Kaladex® PEN films are currently qualified in several applications with further opportunities under development. Samples of the current Kaladex® grade range are available for testing and evaluation, and further grades will follow as the market demands.

Table 1: Properties of Kaladex 2000 PEN film

	Property	Units		Kaladex [®] 2000	Test Method	
	Density	g/cm³		1.36	DTF Method	
Structure	Surface Roughness	nm	Sa	22	DTF Method	
	ourrace riougimess	11111	Sq	33	DTF Method	
	Young's Modulus	MPa	MD TD	6700 6900	ASTM D882	
			MD	150		
	F5	MPa	TD	155	ASTM D882	
	Tanaila Okuanakh	145	MD	245	A CTAA DOOG	
	Tensile Strength	MPa	TD	275	ASTM D882	
Mechanical	Elongation to Break	%	MD	90%	ASTM D882	
Properties	3		TD . MB	70%		
	Tear Initiation	N N	25um in MD 25um in TD	5.5 5.9	ASTM D1004 (50mm/minute) ASTM D1938 (1000mm/minute)	
+			25um in MD	1.5		
	Tear Propagation		25um in TD	1.6		
	Coefficient of Friction		Static	0.43		
			Dynamic	0.37		
	Melting Temperature	°C		265	DTF Method by DSC	
	Glass Transition Temperature (Resin)	°C		121	DTF Method by DSC	
	Glass Transition Temperature (Film)	°C	MD	155 0.6	DTF Method by DMA	
	Shrinkage (150°C for 30 mins)	%	TD	0.6	DTF Method	
Physical and	01 : 1 (2000 (MD	1.2	577.1.1	
Thermal Properties	Shrinkage (190°C for 5 mins)	%	TD	1.4	DTF Method	
	Coefficient of Thermal Expansion	10 ⁻⁶ /°C	MD	13	DTF Method	
	Coefficient of Hygroscopic Expansion	10 ⁻⁶ /%RH	MD	11	DTF Method	
	Continuous Use Temperature (RTI)	°C	Mechanical	160	UL746B (UL File E93687)	
	Maisture Adequation	%	Electrical	180	DTF Mathed (20%C %, E00/, DLI)	
Chemical	Moisture Adsorption Moisture Permeability	g/m².24hr	25um	0.20% 4.3	DTF Method (20°C & 50% RH) ASTM E398	
Properties	Oxygen Permeability	cm ³ /m ² ·24hr.atm	25um	15.2	ASTM D3985	
	Electric Strength		16um	390		
			25um	331		
			38um	261		
		kV/mm	50um	248	ASTM D149	
			75um	198		
			100um 125um	187 163		
			23°C, 50Hz	3.24		
			23°C, 1kHz	3.22		
	Permittivity	-	23°C, 10kHz	3.20	A C.T.M. D.150	
Electrical Properties			50°C, 50Hz	3.27	ASTM D150	
			100°C, 50Hz	3.29		
			150°C, 50Hz	3.40		
			23°C, 50Hz 23°C, 1kHz	0.0034 0.0042		
			23°C, 10kHz	0.0042		
	Dissipation Factor	-	50°C, 50Hz	0.0048	ASTM D150	
			100°C, 50Hz	0.0055		
			150°C, 50Hz	0.0125		
	Surface Resistivity	Log Ω/Sq		15	ASTM D257 (500V d.c., 20°C & 54% RH)	
	Volume Resistivity	Log Ω.m	- MD	16	ASTM D257 (100V d.c., 25°C & 1000s)	
	Refractive Index		nMD nTD	1.75 1.76	DTF Method	
	Heridelive index		nz	1.50	DTI Wediod	
			16um	87		
Optical Properties	Total Light Transmission	%	25um	86		
			38um	85		
			50um	84	ASTM D1003	
			75um	83		
			100um 125um	83 82		
	Wide Angle Haze	%	16um	5		
			25um	6		
			38um	8		
			50um	13	ASTM D1003	
			75um	18		
			100um	25		
			125um	30		

Table 2: Comparison of Kaladex 2000 PEN film with a typical PET film

Property	Units		Kaladex* 2000 PEN film	Typical PET film	Test Method	Key Benefit	
Density	g/cm³		1.36	1.40	DTF Method	PEN offers 3% better area yield than an equivalent PET film	
Young's Modulus	MPa	MD	6700	4800	ASTM D882		
Tourig's Modulus		TD	6900	5000	ASTIN DOOZ		
F5	MPa	MD	150	100	ASTM D882		
13		TD	155	100	ASTIVI DOOZ	PEN is >25% stiffer than an equivalent PET film and exhibits	
Tensile Strength	MPa	MD	245	195	ASTM D882	excellent mechanical properties.	
Terisile Strength	IVIFa	TD	275	235	ASTIVI DOOZ		
Elongation to Break	%	MD	90%	115%	ASTM D882		
Elorigation to break		TD	70%	90%			
Melting Temperature	°C		265	254	DTF Method by DSC		
Glass Transition Temperature (Resin)	°C		121	78	DTF Method by DSC	PEN has excellent heat stability, with a significantly higher Tg and a continuous use temperature that exceeds the requirements for Class F	
Glass Transition Temperature (Film)	°C		155	110	DTF Method by DMA		
Continuous Use Temperature (RTI)	°C	Mechanical	160	105	UL746B (UL File E93687)	(155°C) applications.	
Continuous ose temperature (NTI)		Electrical	180	105	OL/40B (OL File E93067)		
Shrinkage (150°C for 30 mins)	%	MD	0.6	1.2	DTF Method	PEN offers better dimensional stability than PET and can also be	
Similikage (150 C for 50 mins)		TD	0.6	1.0	DTF Method		
Shrinkage (190°C for 5 mins)	%	MD	1.2	2.5	DTF Method	further heat-stabilised (pre-shrunk) if required.	
Sillinkage (190 C for 5 fillins)		TD	1.4	1.5	Dir Method	, ii roquii odi	
Moisture Permeability	g/m².24hr	25um	4	15	ASTM E398		
Oxygen Permeability	cm³/ m²·24hr. atm	25um	15	52	ASTM D3985	PEN has better inherent barrier properties than PET.	
	kV	25um	7.5	6.4*	* 23um for PET	PEN has a higher breakdown voltage than an equivalent PET	
Drookdown Voltogs		50um	12.4	10.0			
Breakdown Voltage		75um	14.8	12.0	IEC 243-1	film providing excellent electrical insulation properties.	
		125um	20.3	16.0			

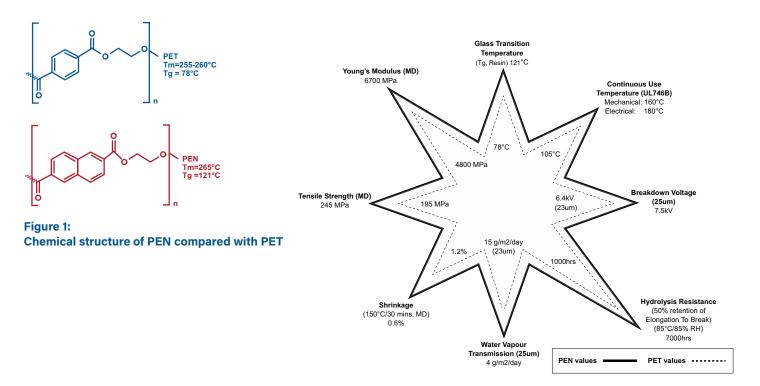


Figure 2: Comparison of key properties between Kaladex PEN and typical PET films

Kaladex® for Electrical Insulation

As the inventor of polyester film DuPont Teijin Films has close to 70 years of experience in the design, development and manufacture of products for a wide range of industries and applications.

One of the earliest to benefit from the property set of polyester films was electrical insulation, with Mylar® becoming the industry standard for high quality PET films offering reliability, consistency and best-in-class properties. Kaladex® PEN films build on this heritage by adding a number of superior properties to the well-known performance of PET films such as Mylar®.

The main grade used in electrical insulation applications is Kaladex* 2000 which exhibits the following key features:

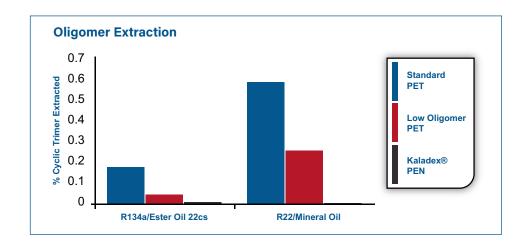
Elevated RTIs of 160°C mechanical and 180°C electrical under UL746B (File E93687)

- Good mechanical strength with stiffness 25% higher than PET
- Excellent dielectric strength (typically 8 x aramid paper)
- Good thermal conductivity (2 x aramid paper at same thickness)
- Greater hydrolysis resistance compared to standard PET
- Low moisture absorption
- Excellent solvent resistance
- Very low oligomer extraction in hermetic motor applications.

These features of Kaladex® PEN film provide a number of benefits in electrical insulation applications:

- RTIs suitable for use in Class F (155°C) applications, with the possibility of use as a system component at higher classes
- Thinner insulation for a given temperature rating, offering:
 - · Reduced cost of insulation
 - Space-saving/size reduction of finished device
 - · Better heat transfer
 - · Reduced cost of other materials
 - New design possibilities for more compact units
 - Easy to handle and laminate in a very similar way to PET films
 - Can be laminated to a range of materials to generate cost-effective higher temperature systems.





Kaladex® for Flexible Printed Circuits

The evolution of Flexible Printed Circuit (FPC) technology along with Flat Flexible Cables (FFC) has greatly benefitted from the development of suitable dielectric film substrates.



Since its inception, FPC/FFC usage has grown steadily based on several inherent characteristics providing advantages in use:

- · Minimal space requirement
- Lower weight than printed circuit boards or round wire
- Placement permitted in restricted areas
- Simplified assembly procedures.

These advantages have driven the adoption of FPC/FFC in numerous applications from military and consumer electronics to automotive dashboards and cabling.

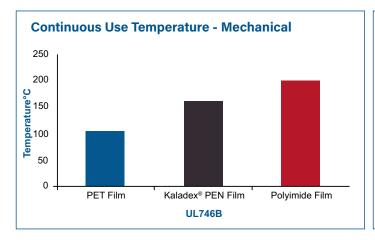
Historically two types of film have been the dominant substrates of choice for FPC applications, polyethylene terephthalate (PET) and polyimide (PI).

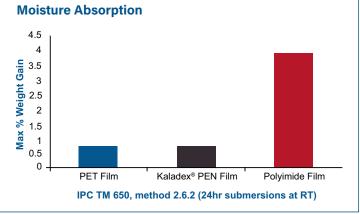
PET films tend to be lower cost and have proven adequate for many applications where the circuit is exposed to moderate environmental conditions.

PI films are significantly more costly but provide better heat resistance and dimensional stability. The resulting gap in performance and economics between PET and PI films is considerable. However, Kaladex® PEN films can provide a very cost-effective solution to bridge this gap, offering a higher level of performance than PET coupled with ease of processing at an attractive price point. Characteristics of Kaladex® PEN films that are highly beneficial to FPC/FFC applications include:

- Glass transition temperature (Tg) of 121°C (as resin), 43°C higher than that of PET films.
- Continuous use temperature mid-way between PET and PI films
- Excellent dimensional stability with lower shrinkage grades available
- Excellent chemical resistance including better resistance to hydrolysis than standard PET films
- · Low levels of moisture absorption.

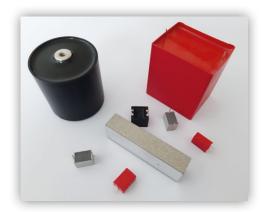
These characteristics position Kaladex® PEN films as an ideal alternative to both PET and PI films. It surpasses PET films in demanding high-end applications and replaces PI films where the combination of performance and cost offered by Kaladex® PEN film can result in considerable savings to the FPC manufacturer. This latter factor is of particular interest in automotive applications where circuits can often have a relatively large area.





Kaladex® for Capacitors

DuPont Teijin Films is the leading supplier of thin PET and PEN films for capacitor dielectrics. Our specialised biaxial stretching process creates a unique balance of mechanical properties and thermal shrinkages that makes them the films of choice for both wound and stacked capacitors.



This process also minimises surface defects and leads to fewer voltage breakdown events in the finished capacitor.

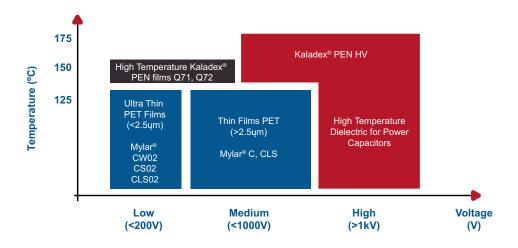
Thin and ultra-thin Kaladex® PEN films extend the performance envelope offered by Mylar® PET films and are particularly suited for applications where a higher service temperature is required, such as surface mount capacitors using lead free solder and automotive lighting.

Kaladex* PEN HV is a thin dielectric for power capacitors under development to provide a high service temperature together with an outstanding breakdown voltage strength, comparable to state of the art dielectric biaxially oriented polypropylene (BOPP).

These unique properties, achieved by sophisticated polymer material science, combine to create a capacitor dielectric offering the highest energy density currently available across a wide range of operating temperatures from -55°C to +175°C.

In addition, when metallised it has excellent self-healing properties. Kaladex® PEN HV is intended for high temperature power applications such as DC link in EV/HEV automotive and avionics, industrial energy conversion and renewable energy. It's high energy density per unit volume and weight allows the most compact capacitor design in power applications combined with high operating temperatures.

Material	Dielectric Constant (25°C, 1kHz)	Dissipation Factor (%) (25°C, 1kHz)	Breakdown Strength (V/mm)	Max. Temp (°C)
Mylar*/Melinex* PET	3.25	0.5	290-350	125
Kaladex [®] PEN	3.05	0.5	280-350	150
Kaladex° PEN HV	2.95	0.3	450-525	175



Kaladex® for other applications

The advanced property set of Kaladex* PEN films has also proved to be highly beneficial for a wide range of additional applications, both established and emerging:



Casting belts and substrates

 Better high temperature performance and improved modulus supports a wider range of applications in more extreme environments.

Image transfer belts for copiers and printers

 High modulus gives a lower tendency to stretch allowing better image definition and increased heat resistance.

High performance loudspeaker diaphragms

 Highly attractive modulus-to-density ratio for better fidelity combined with higher glass transition temperature for use in applications subject to heat.

Dermal patch release liners

 Inherent barrier properties prevent unwanted migration of active ingredients to give a longer shelf life.

High performance sailcloth laminates

• High modulus for better stiffness results in race-winning performance.

Deposition substrate for flexible photovoltaic cells

 High temperature performance allows efficient use of PECVD processes for active layers.

Automotive seat sensors based on membrane touch switch technology

• High glass transition temperature and high modulus resists deformation thereby providing enhanced durability in hot car interiors.

High temperature labels

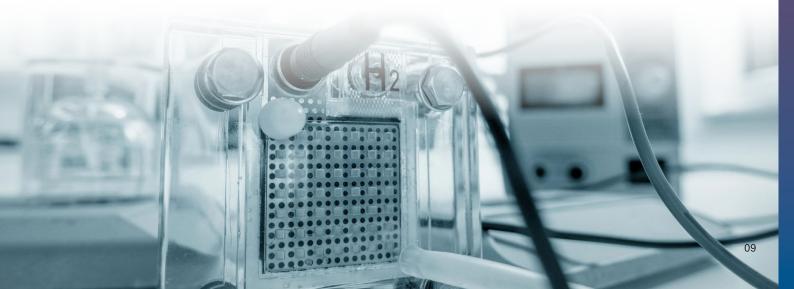
 High temperature performance and better resistance to hydrolysis provides increased durability.

Advanced packaging solutions

 High glass transition temperature, inherent UV screening properties and better barrier allows the design of innovative structures.

Gaskets for fuel cells

• This important emerging technology requires components with reliable high temperature performance and resistance to hydrolysis, ideally suited to the properties of PEN films such as Kaladex*.



Kaladex® Manufacturing Process

Kaladex® PEN films are biaxially oriented and heat set to give a partially crystalline microstructure resulting in excellent mechanical and thermal properties. They are manufactured using the same basic processes as for Mylar® and Melinex® PET films.

Figure 3:
Polyester film manufacturing process – sequential draw (16-125um)

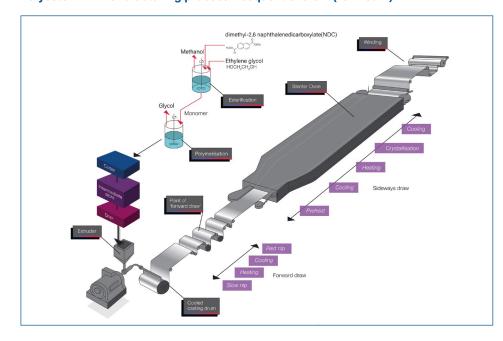


Figure 4:
Polyester film manufacturing process – simultaneous biaxial draw (1.2-12.0um)

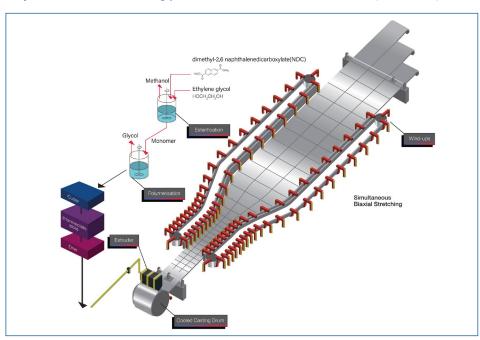


Table 3: Current range of Kaladex PEN films

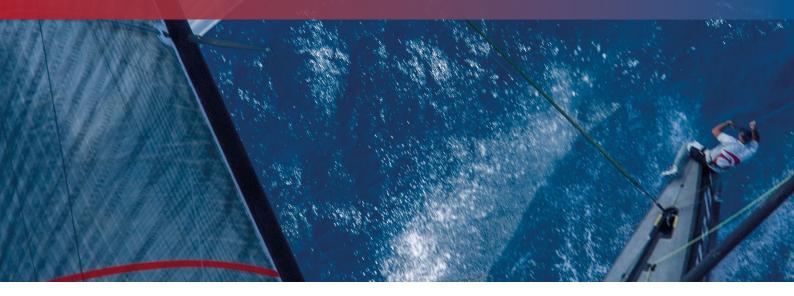
Kaladex [®] Grade Range	Description	Thickness Range
Kaladex° 2000	A slightly hazy PEN film with excellent handling properties. For use in a wide range of applications including electrical insulation and general industrial areas. Kaladex [®] 2000 is the standard grade of PEN film from DuPont Teijin Films.	16, 25, 38, 50, 75, 100 and 125 microns.
Kaladex [°] 2000L	A slightly hazy PEN film with excellent handling properties and carefully controlled lower shrinkage. Designed to be used in applications requiring better dimensional stability, such as flexible printed circuits.	50 microns, with 25 and 125 microns under development. Additional gauges are also possible subject to discussion and sufficient demand.
Kaladex [°] 2021L	A slightly hazy PEN film with excellent handling properties and carefully controlled lower shrinkage, combined with an adhesion promoting pretreatment on one side. The pretreatment offers enhanced adhesion to solvent-based inks, lacquers and adhesives. This film has been designed for use in systems requiring more dimensionally stable PEN substrates coupled with enhanced adhesion, for example fuel cell gaskets.	Under development at 25 microns, with other gauges also possible subject to discussion and sufficient demand.
Kaladex° Q71	Thin PEN film manufactured using a unique biaxial stretching process. Primarily designed as a high performance capacitor dielectric film where higher service temperatures are required, but also suitable for general industrial applications requiring a thinner film.	7-12 microns. With additional gauges also possible subject to discussion and sufficient demand.
Kaladex° Q72	Ultra-thin PEN film manufactured using a unique biaxial stretching process. Designed for use as a high performance capacitor dielectric film where higher service temperatures are required.	1.2-6.0 microns. With additional gauges also possible subject to discussion and sufficient demand.
Kaladex° PEN HV	Ultra-thin PEN film manufactured using a unique biaxial stretching process, designed to provide a market-leading combination of a high service temperature with a significantly higher operating voltage.	Under development at 3-8 microns.

The above listing includes both fully commercial grades and also grades that are at an advanced stage of development. It is our expectation that the development grades listed will be added to the standard grade range in due course, but this cannot be guaranteed. Samples of most Kaladex® grades are available upon application for testing and evaluation.

The market-leading expertise of DuPont Teijin Films in polymer science and film process technology often allows the design of additional products and variants for new applications, and these can be added to the grade range in response to market demand. Please contact us with your requirements.



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Innovation | Partnerships | Sustainability

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